

GaN on SiC HEMT MMIC 16.5 – 21.5GHz 2W Power Amplifier

Typical Applications

- Point-to-Point Radio
- K-Band SATCOM

Features

- Frequency Range: 17.3 20.2 GHz
- Gain: 20 dB
- PAE: 30% @ 35 dBm Pout
- Psat: + 35dBm
- Bias: VD = +28V, IDQ = 100mA, VG = -1.56
- 50Ω Matched Input/Output DC blocked
- Chip Size: 2.4 x 1.8 x 0.1 mm





Electrical Specifications (TA = +25°C, VD = +28V, IDQ = 100mA, VG = -1.72V)

Parameter	Units	Minimum	Typical	Maximum
Frequency	GHz	16.5		21.5
Gain	dB		20	
Gain Flatness	dB		±1	
Input Return Loss	dB		25	
Output Return Loss	dB		16	
PAE	%		30	
Psat	dBm		35	
Supply Voltage (Vdq)	v		+28	
Supply Current (Idq)	mA		100	
DC Dissipated Power	W		2.8	
Package Type			Die	

Datasheet vM040.05



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Performance Graphs



Frequency Response

Power Sweep



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Power vs Supply Voltage

PAE vs Supply Voltage



AM to PM



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Outline Drawing (dimensions in mm)



Pad Descriptions

Pad	Function	Pad Size	Description
1	RFIN	100x200µm	AC coupled 50Ω Matched
2	RFOUT	100x200µm	AC coupled 50Ω Matched
3	VD	214x114µm	Drain Power Supply voltage, bypass capacitors needed*
4	VD2	114x114µm	No connect, Alternate Drain Power Supply voltage
5	VG	114x114µm	Gate Power Supply voltage, bypass capacitors needed*
6	VG2	114x114µm	No connect, Alternate Gate Power Supply voltage
Die Bottom	GND	Backside	Epoxy/Solder to Baseplate

*See Assembly Diagram—Biasing is only required on one side of die

Absolute Maximum Ratings

Drain Bias Voltage (VDD)	+28V DC
RF Input Power (RFIN)	+36dBm*
Channel Temperature	200°C
Storage Temperature	-65 to 150°C
Operating Temperature	-55 to 85°C
**	

*To be tested

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Assembly Diagram



Assembly Notes

- 1. Die Thickness is 100µm
- 2. Backside and Bondpad metallization: 5µm gold
- 3. High thermal conductivity Silver Epoxy or AuSn Eutectic attach MMIC

Die Packaging Information

• GP-4 (Gel-Pak)

Biasing and Operation

The AGM-040 is biased with a positive drain supply and negative gate supply. Performance is optimized when the drain voltage is set to Vdq. The preferred biasing procedure is as follows:

Turn ON procedure:

- 1. Set VG to -3.0V.
- 2. Set VD to Vdq.
- 3. Adjust VG more positive until Id = Idq.
- 4. Apply RF signal.



Turn OFF procedure:

- 1. Turn off RF signal.
- 2. Reduce VG to -3.0V. Id should be 0mA.
- 3. Turn off VD.
- 4. Turn off VG.

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